PCA9561

Quad 6-bit multiplexed I²C-bus EEPROM DIP switch

Rev. 4 — 6 November 2012 Product data sheet

1. General description

The PCA9561 is a 20-pin CMOS device consisting of four 6-bit non-volatile EEPROM registers, six hardware pin inputs and a 6-bit multiplexed output. It is used for DIP switch-free or jumper-less system configuration and supports Mobile and Desktop VID Configuration, where five preset values (four sets of internal non-volatile registers and one set of external hardware pins) set processor voltage for operation in various performance or battery conservation sleep modes. The PCA9561 is also useful in server and telecommunications/networking applications when used to replace DIP switches or jumpers, since the settings can be easily changed via I²C-bus/SMBus without having to power down the equipment to open the cabinet. The non-volatile memory retains the most current setting selected before the power is turned off.

The PCA9561 typically resides between the CPU and Voltage Regulator Module (VRM) when used for CPU VID (Voltage IDentification code) configuration. It is used to bypass the CPU-defined VID values and provide a different set of VID values to the VRM, if an increase in the CPU voltage is desired. An increase in CPU voltage combined with an increase in CPU frequency leads to a performance boost of up to 7.5 %. Lower CPU voltage reduces power consumption. The main advantage of the PCA9561 over older devices, such as the PCA9559 or PCA9560, is that it contains four internal non-volatile EEPROM registers instead of just one or two, allowing five independent settings which allows a more accurate CPU voltage tuning depending on specific applications.

The PCA9561 has two address pins, allowing up to four devices to be placed on the same I²C-bus or SMBus.

2. Features and benefits

- Selection of non-volatile register_n as source to MUX_OUT pins via I²C-bus
- I²C-bus can override MUX_SELECT pin in selecting output source
- 6-bit 5-to-1 multiplexer DIP switch
- Four internal non-volatile registers
- Internal non-volatile registers programmable and readable via I²C-bus
- Six open-drain multiplexed outputs
- 400 kHz maximum clock frequency
- Operating supply voltage 3.0 V to 3.6 V
- 5 V and 2.5 V tolerant inputs/outputs
- Useful for Speed Step configuration of laptop computer
- Two address pins, allowing up to four devices on the I²C-bus
- MUX_IN values readable via I²C-bus

- ESD protection exceeds 200 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JESDEC Standard JESD78 which exceeds 100 mA

3. Ordering information

Table 1. Ordering information

T_{amb} = −40 °C to +85 °C.

Type number	Topside marking	Package		
		Name	Description	Version
PCA9561PW	PCA9561	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1

3.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
PCA9561PW	PCA9561PW,118	TSSOP20	Reel pack, SMD, 13-inch	2500	T_{amb} = −40 °C to +85 °C
	PCA9561PW,112	TSSOP20	Tube, Bulk	1875	T_{amb} = −40 °C to +85 °C

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4. Block diagram

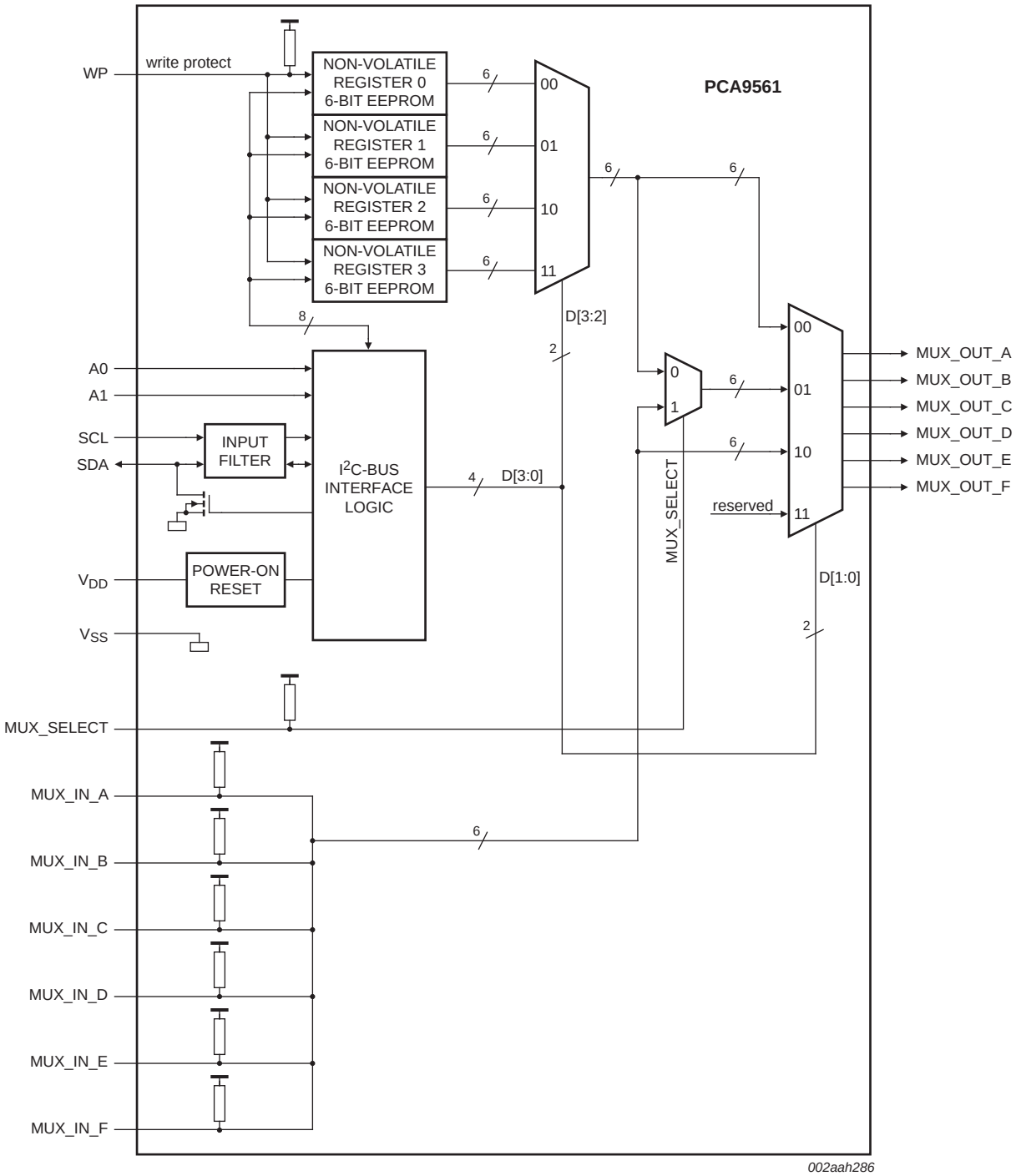


Fig 1. Block diagram of PCA9561

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5. Pinning information

5.1 Pinning

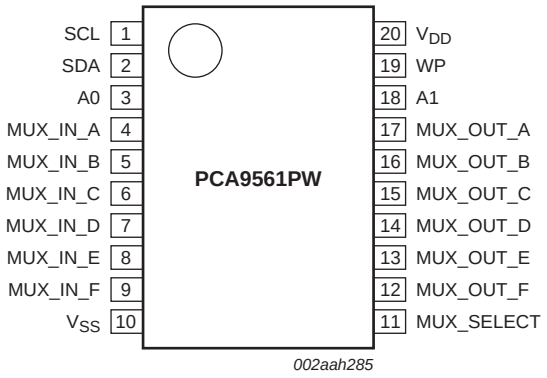


Fig 2. Pin configuration for TSSOP20

5.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
SCL	1	serial I²C-bus clock line
SDA	2	serial bidirectional I²C-bus data line
A0	3	address 0
MUX_IN_A	4	external input A to multiplexer
MUX_IN_B	5	external input B to multiplexer
MUX_IN_C	6	external input C to multiplexer
MUX_IN_D	7	external input D to multiplexer
MUX_IN_E	8	external input E to multiplexer
MUX_IN_F	9	external input F to multiplexer
V_{SS}	10	ground
MUX_SELECT	11	selects MUX_IN_X inputs or EEPROM register contents for MUX_OUT_X outputs
MUX_OUT_F	12	open-drain multiplexed output F
MUX_OUT_E	13	open-drain multiplexed output E
MUX_OUT_D	14	open-drain multiplexed output D
MUX_OUT_C	15	open-drain multiplexed output C
MUX_OUT_B	16	open-drain multiplexed output B
MUX_OUT_A	17	open-drain multiplexed output A
A1	18	address 1
WP	19	non-volatile register write-protect
V_{DD}	20	supply voltage (3.0 V to 3.6 V)

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6. Functional description

Refer to Figure 1 “Block diagram of PCA9561”.

6.1 Device address

Following a START condition the bus master must output the address of the slave it is accessing. The address of the PCA9561 is shown in Figure 3. To conserve power, no internal pull-up resistors are incorporated on the hardware selectable address pins and they must be pulled HIGH or LOW.

The last bit of the slave address byte defines the operation to be performed. When set to logic 1 a read is selected, while a logic 0 selects a write operation.

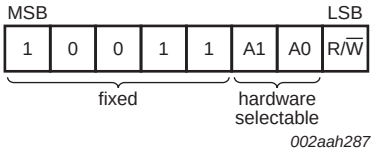


Fig 3. Slave address

6.2 Control register

Following the successful acknowledgement of the slave address, the bus master will send a byte to the PCA9561, which will be stored in the Control register. This register can be written and read via the I²C-bus.

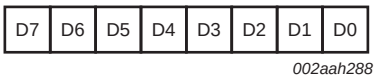


Fig 4. Control register

6.2.1 Control register definition

Following the address and acknowledge bit with logic 0 in the read/write bit, the first byte written is the command byte. If the command byte is reserved and therefore not valid, it will not be acknowledged. Only valid command bytes will be acknowledged.

Table 4. Address register

D7	D6	D5	D4	D3	D2	D1	D0	Register name	Type	Register function
0	0	0	0	0	0	0	0	EEPROM_0	read/write	EEPROM byte 0 register
0	0	0	0	0	0	0	1	EEPROM_1	read/write	EEPROM byte 1 register
0	0	0	0	0	0	1	0	EEPROM_2	read/write	EEPROM byte 2 register
0	0	0	0	0	0	1	1	EEPROM_3	read/write	EEPROM byte 3 register
1	1	1	1	1	1	1	1	MUX_IN	read	MUX_IN values register

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Table 5. Commands register

All other combinations are reserved.

Command value								Command function	
D7	D6	D5	D4	D3	D2	D1	D0	MUX_SELECT = 1	MUX_SELECT = 0
1	1	1	1	0	0	0	0	EEPROM byte 0	EEPROM byte 0
1	1	1	1	0	1	0	0	EEPROM byte 1	EEPROM byte 1
1	1	1	1	1	0	0	0	EEPROM byte 2	EEPROM byte 2
1	1	1	1	1	1	0	0	EEPROM byte 3	EEPROM byte 3
1	1	1	1	0	0	0	1	MUX_IN	EEPROM byte 0
1	1	1	1	0	1	0	1	MUX_IN	EEPROM byte 1
1	1	1	1	1	0	0	1	MUX_IN	EEPROM byte 2
1	1	1	1	1	1	0	1	MUX_IN	EEPROM byte 3
1	1	1	1	X	X	1	0	MUX_IN	MUX_IN

6.3 Register description

If the Control register byte is an EEPROM address, the next byte will be programmed into that EEPROM address on the following STOP condition, if WP is logic 0. If more than one byte is sent sequentially, the second byte will be written in the other volatile register, on the following STOP condition. Up to four bytes can be sent sequentially. If any more data bytes are sent after the fourth byte, they will not be acknowledged and no bytes will be written to the non-volatile registers. After a byte is read from or written to the EEPROM, the part automatically points to the next non-volatile register. If the Command register code was FFh, the MUX_IN values are sent with the two MSBs padded with zeros as shown below. If the command register code is 00h, then the non-volatile register 0 is sent. If the command register code is 01h, then the non-volatile register 1 is sent. If the command register code is 02h, then the non-volatile register 2 is sent. If the command register code is 03h, then the non-volatile register 3 is sent.

Table 6. EEPROM byte 0 register

	D7	D6	D5	D4	D3	D2	D1	D0
Write	X	X	EEPROM 0 data F	EEPROM 0 data E	EEPROM 0 data D	EEPROM 0 data C	EEPROM 0 data B	EEPROM 0 data A
Read	0	0	EEPROM 0 data F	EEPROM 0 data E	EEPROM 0 data D	EEPROM 0 data C	EEPROM 0 data B	EEPROM 0 data A
Default	0	0	0	0	0	0	0	0

Table 7. EEPROM byte 1 register

	D7	D6	D5	D4	D3	D2	D1	D0
Write	X	X	EEPROM 1 data F	EEPROM 1 data E	EEPROM 1 data D	EEPROM 1 data C	EEPROM 1 data B	EEPROM 1 data A
Read	0	0	EEPROM 1 data F	EEPROM 1 data E	EEPROM 1 data D	EEPROM 1 data C	EEPROM 1 data B	EEPROM 1 data A
Default	0	0	0	0	0	0	0	0

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Table 8. EEPROM byte 2 register

	D7	D6	D5	D4	D3	D2	D1	D0
Write	X	X	EEPROM 2 data F	EEPROM 2 data E	EEPROM 2 data D	EEPROM 2 data C	EEPROM 2 data B	EEPROM 2 data A
Read	0	0	EEPROM 2 data F	EEPROM 2 data E	EEPROM 2 data D	EEPROM 2 data C	EEPROM 2 data B	EEPROM 2 data A
Default	0	0	0	0	0	0	0	0

Table 9. EEPROM byte 3 register

	D7	D6	D5	D4	D3	D2	D1	D0
Write	X	X	EEPROM 3 data F	EEPROM 3 data E	EEPROM 3 data D	EEPROM 3 data C	EEPROM 3 data B	EEPROM 3 data A
Read	0	0	EEPROM 3 data F	EEPROM 3 data E	EEPROM 3 data D	EEPROM 3 data C	EEPROM 3 data B	EEPROM 3 data A
Default	0	0	0	0	0	0	0	0

Table 10. MUX_IN register

	D7	D6	D5	D4	D3	D2	D1	D0
Read	0	0	MUX_IN data F	MUX_IN data E	MUX_IN data D	MUX_IN data C	MUX_IN data B	MUX_IN data A

If the command register is a command byte, any additional data bytes sent after the command register will not be acknowledged. If the read/write bit in the address is a logic 1, then a read operation follows and the data sent out depends on the previously stored step.

After a valid I²C-bus write operation to the EEPROM, the part cannot be addressed via the I²C-bus for 3.6 ms. If the part is addressed prior to this time, the part will not acknowledge its address.

Remark: To ensure data integrity, the non-volatile register must be internally write-protected when V_{DD} to the I²C-bus is powered down or V_{DD} to the component is dropped below normal operating levels.

6.4 External control signals

The Write Protect (WP) input is used to control the ability to write the content of the non-volatile registers. If the WP signal is logic 0, the I²C-bus will be able to write the contents of the non-volatile registers. If the WP signal is logic 1, data will not be allowed to be written into the non-volatile registers. In this case, the slave address and the command code will be acknowledged, but the following data bytes will not be acknowledged and the EEPROM is not updated.

The factory defaults for the contents of the non-volatile register are all logic 0. These stored values can be read or written using the I²C-bus (described in Section 7 “Characteristics of the I²C-bus”).

The WP, MUX_IN_X, and MUX_SELECT signals have internal pull-up resistors. See Table 15 “Static characteristics” and Table 16 “Dynamic characteristics” for hysteresis and signal spike suppression figures.

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Table 11. Function table

This table is valid when not overridden by I²C-bus control register.

Input		Commands
WP	**MUX_SELECT**	
0	X	Write to the non-volatile registers through I²C-bus allowed
1	X	Write to the non-volatile registers through I²C-bus not allowed
X	0	MUX_OUT_X from EEPROM byte 0 to byte 3 (EEPROM selected through I²C-bus; refer to Table 5 “Commands register”)
X	1	MUX_OUT_X from MUX_IN_X inputs

6.5 Power-on reset

When power is applied to V_{DD}, an internal Power-On Reset (POR) holds the PCA9561 in a reset state until V_{DD} has reached V_{POR}. At that point, the reset condition is released and the PCA9561 volatile registers and state machine will initialize to their default states.

The MUX_OUT_X pin values depend on the MUX_SELECT logic level:

- If MUX_SELECT = 0, the MUX_OUT_X pin output values will equal the previously stored EEPROM byte 0 values regardless of the last non-volatile EEPROM byte selected by the command byte prior to power-down.
- If MUX_SELECT = 1, the MUX_OUT_X output values will equal the MUX_IN_X pin input values as shown in Table 11 “Function table”.

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7. Characteristics of the I²C-bus

The I²C-bus is for 2-way, 2-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL). Both lines must be connected to a positive supply via a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

7.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this time will be interpreted as control signals (see Figure 5).

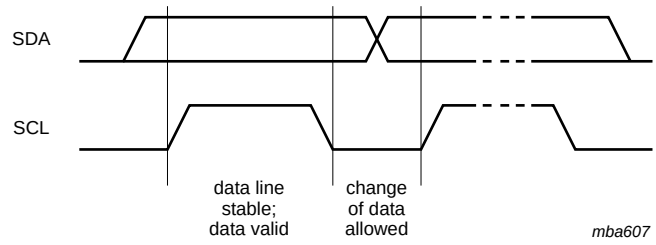


Fig 5. Bit transfer

7.1.1 START and STOP conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line while the clock is HIGH is defined as the START condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH is defined as the STOP condition (P) (seeFigure 6.)

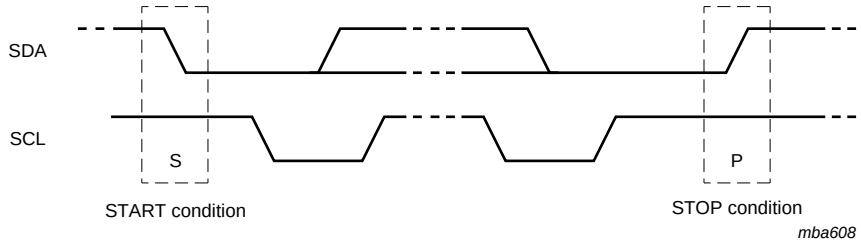


Fig 6. Definition of START and STOP conditions

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7.2 System configuration

A device generating a message is a ‘transmitter’; a device receiving is the ‘receiver’. The device that controls the message is the ‘master’ and the devices which are controlled by the master are the ‘slaves’ (see Figure 7).

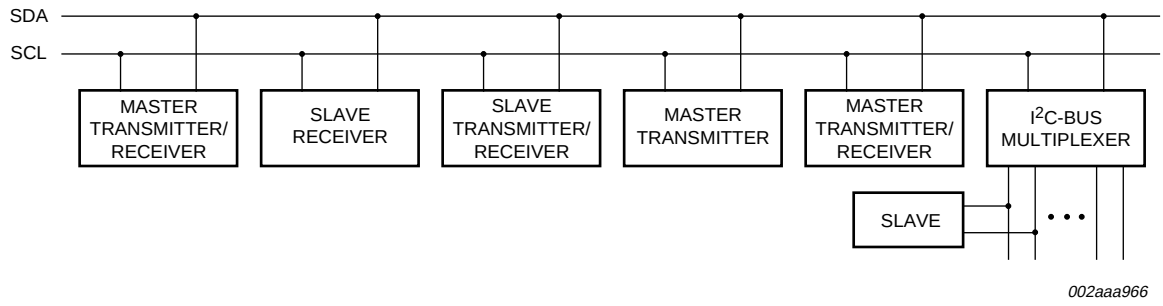


Fig 7. System configuration

7.3 Acknowledge

The number of data bytes transferred between the START and the STOP conditions from transmitter to receiver is not limited. Each byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter, whereas the master generates an extra acknowledge related clock pulse.

A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges has to pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse; set-up and hold times must be taken into account.

A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this event, the transmitter must leave the data line HIGH to enable the master to generate a STOP condition.

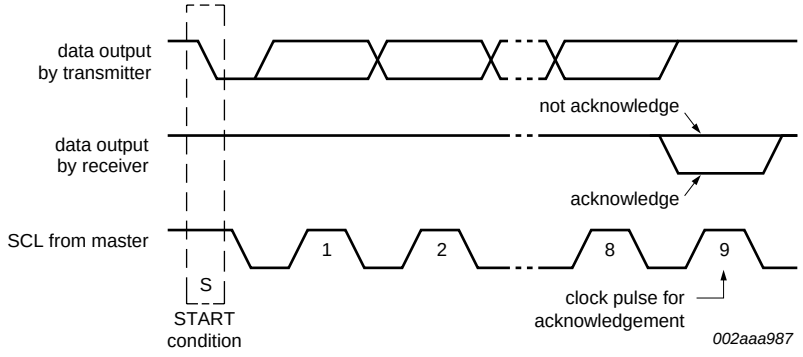


Fig 8. Acknowledgement on the I²C-bus

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7.4 Bus transactions

Data is transmitted to the PCA9561 registers using the Write Byte transfers (see Figure 9 and Figure 10. Data is read from PCA9561 using Read and Receive Byte transfers (see Figure 11).

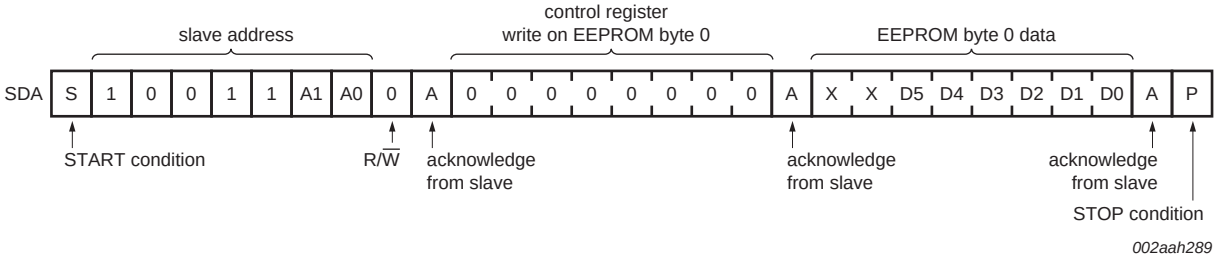


Fig 9. Write on one EEPROM, assuming WP = 0

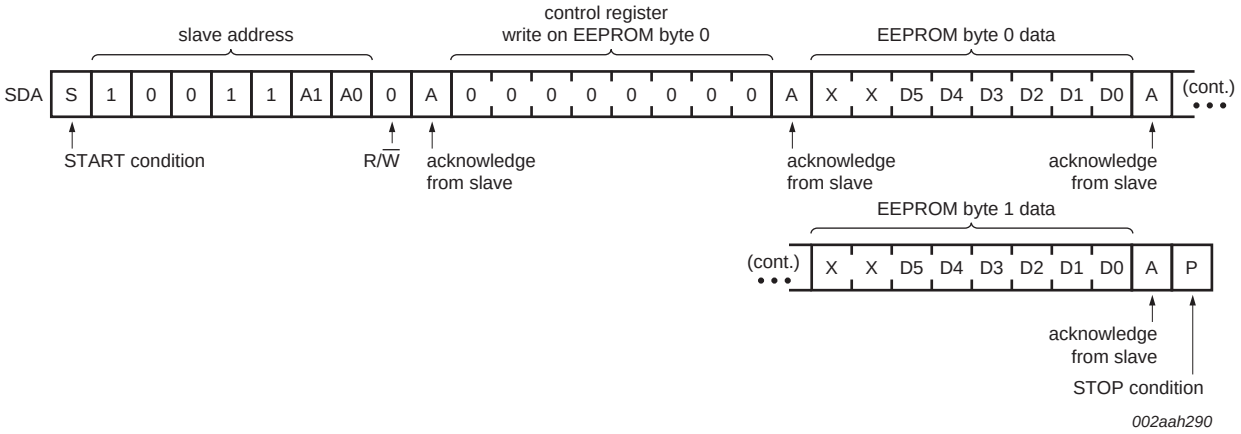


Fig 10. Write on two EEPROMs, assuming WP = 0

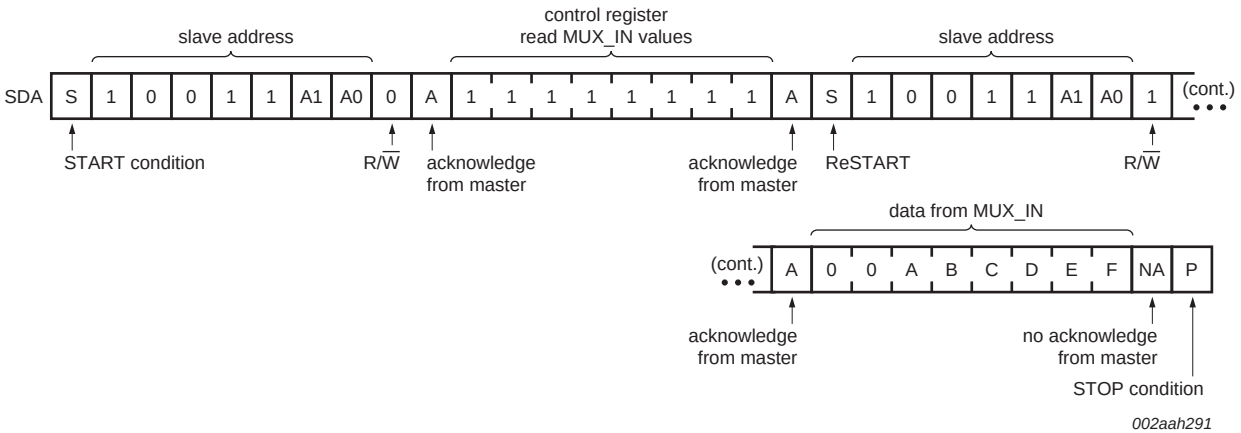


Fig 11. Read MUX_IN register

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8. Limiting values

Table 12. Limiting values[1]

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		−0.5	+4.0	V
V_I	input voltage		−1.5	+5.5[2]	V
V_O	output voltage		−0.5	+5.5[2]	V
T_{stg}	storage temperature		−60	+150	°C

[1] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

[2] The maximum input or output voltage is the lesser of 5.5 V or V_{DD} + 4.0 V, except for very short durations (for example, system start-up or shut-down).

9. Recommended operating conditions

Table 13. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		3.0	3.6	V
V_{IL}	LOW-level input voltage	SCL, SDA; I_{OL} = 3 mA	−0.5	+4.0	V
V_{IH}	HIGH-level input voltage	SCL, SDA; I_{OL} = 3 mA	2.7	5.5[1]	V
V_{OL}	LOW-level output voltage	SCL, SDA			
		I_{OL} = 3 mA	-	0.4	V
		I_{OL} = 6 mA	-	0.6	V
V_{IL}	LOW-level input voltage	MUX_IN_X, MUX_SELECT	−0.5	+0.8	V
V_{IH}	HIGH-level input voltage	MUX_IN_X, MUX_SELECT	2.0	5.5[1]	V
I_{OL}	LOW-level output current	MUX_OUT_X	-	8	mA
I_{OH}	HIGH-level output current	MUX_OUT_X	-	100	µA
$\Delta t/\Delta V$	input transition rise and fall rate		0	10	ns/V
T_{amb}	ambient temperature	operating in free air	−40	+85	°C

[1] The maximum input voltage is the lesser of 5.5 V or V_{DD} + 4.0 V, except for very short durations (for example, system start-up or shut-down).

10. Thermal characteristics

Table 14. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	TSSOP20 package	146	°C/W

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11. Static characteristics

Table 15. Static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply						
V_{DD}	supply voltage		3	-	3.6	V
I_{DD}	supply current	operating mode				
		all inputs = 0 V	-	0.6	1	mA
		all inputs = V_{DD}	-	-	600	μA
V_{POR}	power-on reset voltage	no load; $V_I = V_{DD}$ or V_{SS}	-	2.3	2.7	V
Input SCL; input/output SDA						
V_{IL}	LOW-level input voltage		–0.5	-	+0.8	V
V_{IH}	HIGH-level input voltage		2	-	5.5[1]	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V	3	-	-	mA
		V_{OL} = 0.6 V	6	-	-	mA
I_{LIH}	HIGH-level input leakage current	$V_I = V_{DD}$	–1	-	+1	μA
I_{LIL}	LOW-level input leakage current	$V_I = V_{SS}$	–1	-	+1	μA
C_i	input capacitance		-	3	6	pF
WP; MUX_SELECT						
I_{LIH}	HIGH-level input leakage current	$V_I = V_{DD}$	–1	-	+1	μA
I_{LIL}	LOW-level input leakage current	V_{DD} = 3.6 V; $V_I = V_{SS}$	–20	-	–50	μA
C_i	input capacitance		-	2.5	5	pF
MUX_IN_A, MUX_IN_B, MUX_IN_C, MUX_IN_D, MUX_IN_E, MUX_IN_F						
I_{LIH}	HIGH-level input leakage current	$V_I = V_{DD}$	–1	-	+1	μA
I_{LIL}	LOW-level input leakage current	V_{DD} = 3.6 V; $V_I = V_{SS}$	–20	-	–50	μA
C_i	input capacitance		-	2.5	5	pF
Inputs A0, A1						
I_{LIH}	HIGH-level input leakage current	$V_I = V_{DD}$	–1	-	+1	μA
I_{IL}	LOW-level input current	V_{DD} = 3.6 V; $V_I = V_{SS}$	–20	-	–50	μA
C_i	input capacitance		-	2	4	pF
MUX_OUT_A, MUX_OUT_B, MUX_OUT_C, MUX_OUT_D, MUX_OUT_E, MUX_OUT_F						
V_{OL}	LOW-level output voltage	I_{OL} = 100 μA	-	-	0.4	V
		I_{OL} = 4 mA	-	-	0.7	V
I_{OH}	HIGH-level output current	$V_{OH} = V_{DD}$	-	-	100	μA

[1] The maximum input voltage is the lesser of 5.5 V or V_{DD} + 4.0 V, except for very short durations (for example, system start-up or shut-down).

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12. Dynamic characteristics

Table 16. Dynamic characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
MUX_IN_X → MUX_OUT_X						
t_{PLH}	LOW to HIGH propagation delay		-	28	40	ns
t_{PHL}	HIGH to LOW propagation delay		-	8	15	ns
MUX_SELECT → MUX_OUT_X						
t_{PLH}	LOW to HIGH propagation delay		-	30	43	ns
t_{PHL}	HIGH to LOW propagation delay		-	10	15	ns
t_r	rise time	output	1.0	-	3	ns/V
t_f	fall time	output	1.0	-	3	ns/V
C_L	load capacitance	test load on outputs	-	-	50	pF

Table 17. I²C-bus dynamic characteristics

Symbol	Parameter	Conditions	Standard-mode I²C-bus		Fast-mode I²C-bus		Unit
			Min	Max	Min	Max	
f_{SCL}	SCL clock frequency		0	100	0	400	MHz
t_{BUF}	bus free time between a STOP and START condition		4.7	-	1.3	-	µs
$t_{HD;STA}$	hold time (repeated) START condition		4.0	-	0.6	-	µs
t_{LOW}	LOW period of the SCL clock		4.7	-	1.3	-	µs
t_{HIGH}	HIGH period of the SCL clock		4.0	-	0.6	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition		4.7	-	0.6	-	µs
$t_{HD;DAT}$	data hold time		0[1]	3.45	0[1]	0.9	µs
$t_{SU;DAT}$	data set-up time		250	-	100	-	ns
t_r	rise time of both SDA and SCL signals		-	1000	$20 + 0.1C_b$[2]	300	ns
t_f	fall time of both SDA and SCL signals		-	300	$20 + 0.1C_b$[2]	300	ns
$t_{SU;STO}$	set-up time for STOP condition		4.0	-	0.6	-	µs
C_b	capacitive load for each bus line		-	400	-	400	pF
t_{SP}	pulse width of spikes that must be suppressed by the input filter		-	50	-	50	ns

[1] A device must internally provide a hold time of at least 300 ns for the SDA signal (referred to the $V_{IH(min)}$ of the SCL signal) in order to bridge the undefined region of the falling edge of SCL.

[2] C_b = total capacitance of one bus line in pF.

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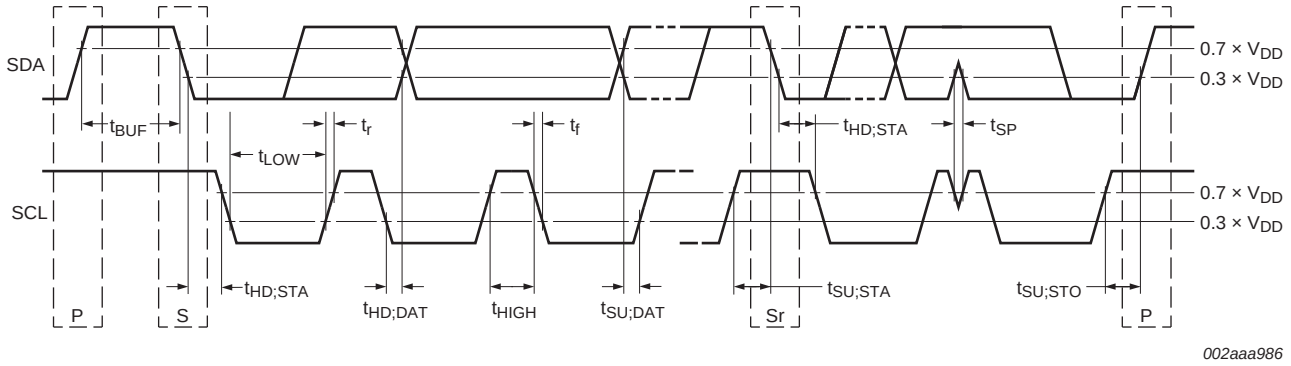


Fig 12. Definition of timing

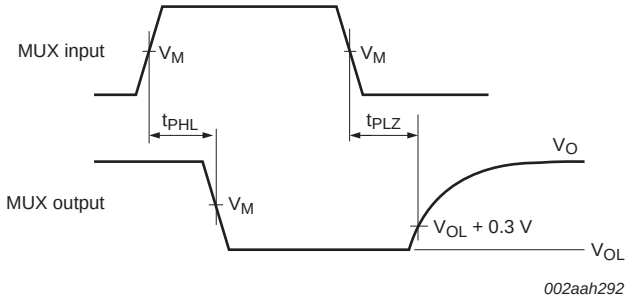


Fig 13. Open-drain output enable and disable times

13. Non-volatile storage specifications

Table 18. Non-volatile storage specifications

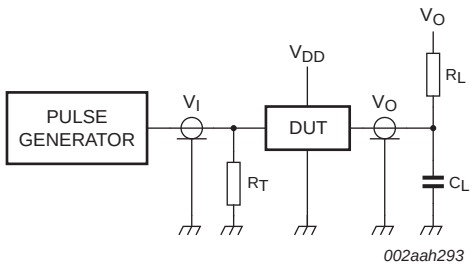
Parameter	Specification
memory cell data retention	10 years (minimum)
number of memory cell write cycles	100,000 cycles (minimum)

Application note *AN250, "I2C DIP Switch"* provides additional information on memory cell data retention and the minimum number of write cycles.

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14. Test information



R_L = load resistor; 1 kΩ.

C_L = load capacitance; includes jig and probe capacitance; 10 pF.

R_T = termination resistance; should be equal to Z_o of pulse generators.

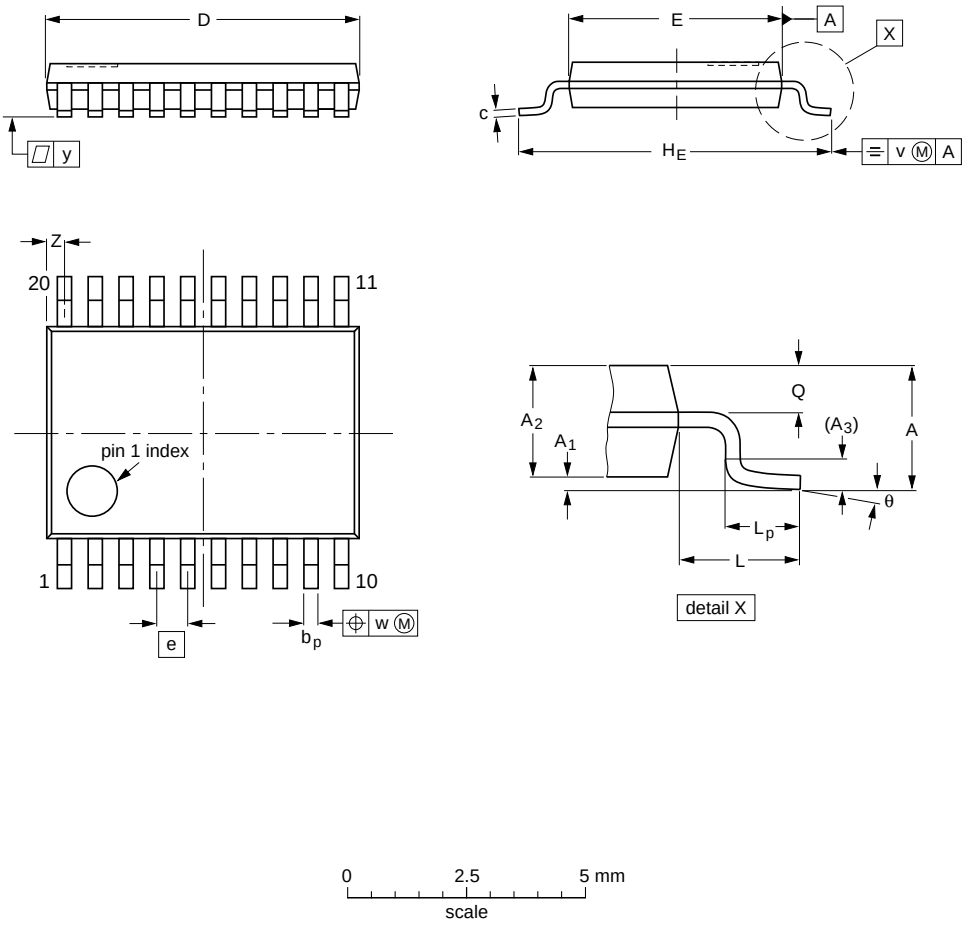
Fig 14. Test circuit for open-drain outputs

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15. Package outline

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 15. Package outline SOT360-1 (TSSOP20)

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16. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

16.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

16.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

16.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

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16.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 16) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 19 and 20

Table 19. SnPb eutectic process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 20. Lead-free process (from J-STD-020C)

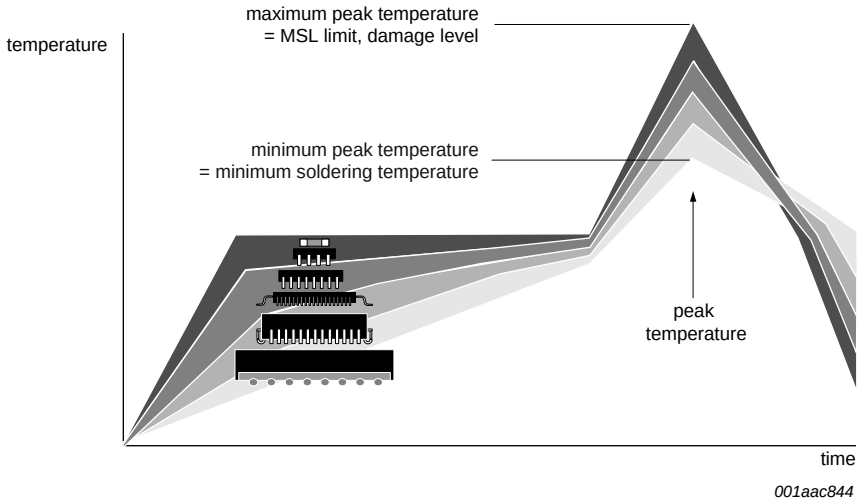
Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 16.

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MSL: Moisture Sensitivity Level

Fig 16. Temperature profiles for large and small components

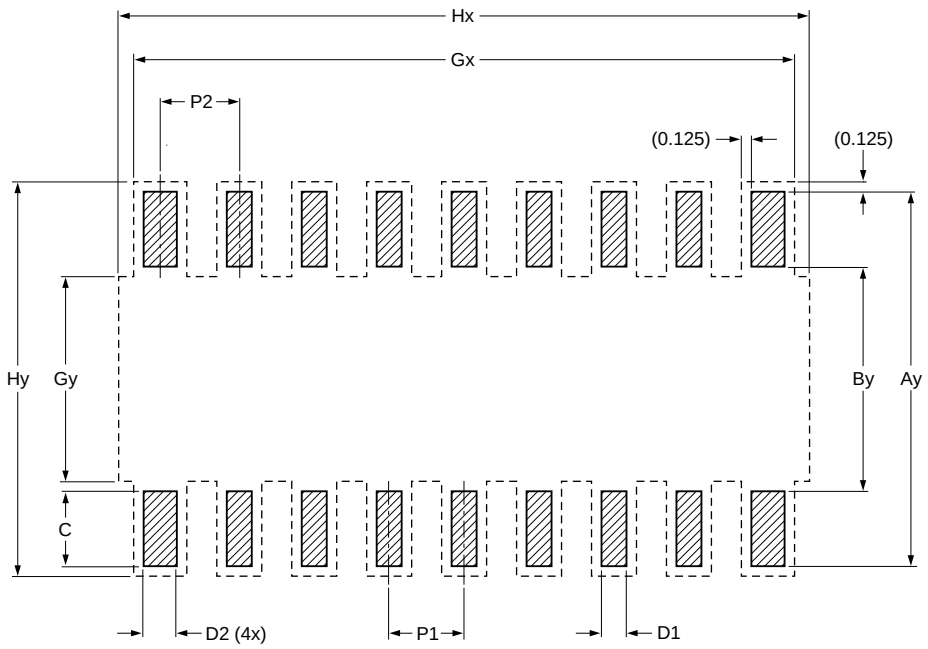
For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

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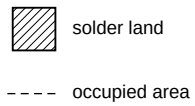
17. Soldering: PCB footprints

Footprint information for reflow soldering of TSSOP20 package **SOT360-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout



DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	6.900	5.300	7.300	7.450

sot360-1_fr

Fig 17. PCB footprint for SOT360-1 (TSSOP20); reflow soldering

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18. Abbreviations

Table 21. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal-Oxide Semiconductor
CPU	Central Processing Unit
DIP	Dual In-line Package
EEPROM	Electrically Erasable Programmable Read-Only Memory
ESD	ElectroStatic Discharge
HBM	Human Body Model
I^2C-bus	Inter-Integrated Circuit bus
PCB	Printed-Circuit Board
SMBus	System Management Bus
VID	Voltage IDentification code
VRM	Voltage Regulator Module

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19. Revision history

Table 22. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9561 v.4	20121106	Product data sheet	-	PCA9561 v.3
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Symbol/Parameter combinations are adapted to new NXP presentation standards • Section 2 “Features and benefits”, 13th bullet item: deleted phrase “200 V MM per JESD22-A115” • Table 1 “Ordering information”: deleted PCA9561D (SO20) package option • Added Section 3.1 “Ordering options” • Table 3 “Pin description”, – pin 10 name changed from “GND” to “V_{SS}” – MUX_SELECT description modified: changed from “inputs of register contents” to “inputs of EEPROM register contents” • Figure 1 “Block diagram of PCA9561” modified • Table 4 title changed from “Register Addresses” to “Address register” • Table 5 “Commands register” rewritten • Section 6.3 “Register description”: – first paragraph rewritten – second paragraph (follows Table 9) rewritten – deleted (old) third paragraph – deleted (old) fourth paragraph • Figure 11 “Read MUX_IN register” modified: ‘data from MUX_IN’ byte changed from “00043210” to “00ABCDEF” • Added Section 10 “Thermal characteristics” • Table 16 “Dynamic characteristics”: added C_L Max value (50 pF) • Figure 13 “Open-drain output enable and disable times”: corrected label from “t_{PLZ}” to “t_{PLH}” • Added Section 16 “Soldering of SMD packages” • Added Section 17 “Soldering: PCB footprints”			
PCA9561 v.3 (9397 750 13153)	20040517	Product data sheet	-	PCA9561 v.2
PCA9561 v.2 (9397 750 11677)	20030627	Product data	ECN 853-2348 29936 of 19 May 2003	PCA9561 v.1
PCA9561 v.1 (9397 750 09888)	20020524	Product data	ECN 853-2348 28311 of 24 May 2002	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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